

KY8030-3

The Industry's Fastest True 3D Solder Paste Inspection Solution

The KY8030-3 is back, faster than ever using Koh Young's 3D dual-inspection technology to eliminate critical shadow problems while enhancing productivity and speeding up the production process.



Zero-defect through AI-Powered Koh Young Process Optimizer(KPO) KORYOUNG

KY8030-3The Industry's Fastest True 3D
Solder Paste Inspection Solution



Unmatched Inspection Speed with Guaranteed Best Accuracy

 The KY8030-3 blends Koh Young's pioneering technologies with an inspection speed of 91.2cm²/sec. The combination of this system's throughput and accuracy makes the KY8030-3 suitable across a vast range of applications. The latest options makes this system twice as fast as its predecessor with guaranteed measurement accuracy.





Active Warp Compensation

Z-tracking 3D compensation

The unique Koh Young warp compensation technology actively calculates and detects any substrate warpage. Using its exclusive 3D imaging and algorithms, Koh Young considers multiple elements like slope, stretch, twist, bow, and shrinkage to guarantee an accurate measurement and to meet the ultimate inspection system criteria.

Pad-referencing 2D compensation (optional)

Real-time, automatic reference teaching uses IR lighting to compensate for non-linear inspection challenges by analyzing the PCB pad locations against the ideal PCB stencil design defined in the CAD file.





Automated Solder Paste Dispensing: Auto-Rework

• KY8030-3 dispenses solder paste automatically as an optional add-on solution. The high-precision and user-friendly dispensing system helps eliminate costly mistakes due in large part to insufficient solder in open joints, lean fillets, and weak joints. The automatic dispensing option reduces operational costs, improves line efficiency, and strengthens profitability by eliminating board scrap and rework. Once Koh Young's SPI is configured with the Auto-Rework option, it becomes more than an inspection system. It becomes a true process optimizer.

Test Results	Small Sized	Pad	Test Resu	ılts	BGA P	ad		
NG	Bef	ore	O O NG	-	Before			
	Volume	30.24 %	0.0.0		Volume	22.4 %		
	Height	86.68 um			Height	51.86 um		
	Area	31.4 %			Area	38.87 %		
	Offset X	0.001 mm			Offset X	-0.001 mm		
1 M M M M	Offset Y	-0.008 mm			Offset Y	0.004 mm		
					• • • • • • • • • • • • • • • • • • •			
Good	Aft	ter	e e Good		A	fter		
	Volume	78.38 %	0.0.0		Volume	74.64 %		
ि लिंग 🛁 🖉 🖉	Height	92.26 um		100 M	Height	71.71 um		
	Area	76.46 %			Area	93.68 %		
N N	Offset X	0.001 mm	000		Offset X	-0.001 mm		
1 10 10 10 <u>10</u>	Offset Y	-0.005 mm			Offset Y	0.004 mm		

KSMART Solutions: True 3D Measurement-based Process Control System

- Koh Young pioneered True 3D measurement technology 20 years ago to create a zero-defect future. This gave rise to KSMART Solutions and its continuous efforts to leverage data and connectivity.
- KSMART Solutions uses Artificial Intelligence to help automate process control while focusing on data management, analysis, and optimization. It collects data from across the factory line for defect detection, realtime optimization, enhanced decisions, and traceability to improve metrics, increase quality, and lower costs by eliminating variance, false calls, and escapes.

"KSMART Solutions is the Gateway to a Smart Factory"

- Converts data into knowledge for effective and quality-driven actions
- Delivers an AI-powered process analysis and optimization tool
- Achieves an autonomous process optimization facility





Zero-defect through AI-Powered Koh Young Process Optimizer (KPO)

 Koh Young is driven to help customers achieve a Zero-defect print process scenario. The AI-powered Koh Young Process Optimizer (KPO) solution automatically exercises complex algorithms to develop and implement print process improvements. By actively monitoring the print process, KPO sends operators realtime performance diagnostics and threshold alerts – it even implements process change automatically. KPO ensures real-time print process reliability without dedicated experts.



Specification

	Re	quirements		Solutions							
Solution to Shadow Problem					3D Shadow Free Moiré Technology & Dual Projection						
PCB Warp Compensation (2D + 3D Solution)					Active Warp Compensation (Z-Tracking & Pad Referencing (Optional))						
	User Fi	riendly Operation			F	Renewal GUI, Real Color 3D I	mage				
	Whole-board Fe	oreign Material Ins	ection 3D Foreign Material Inspection								
Inspection Metrology Capability		Volume, Area, Height, Offset, Bridging, Shape Deformity, Paste Offset, Coplanarity									
Items Types of Defects		Insufficient, Exces	Insufficient, Excessive, Missing Paste, Bridging, Shape Deformity, Paste Offset, Coplanarity								
	Model	Camera & Resolution	FOV Size	Full 3	D Inspection Speed	Minimum Distance Between Pads	Inspection Height (Max & Min)				
	KY8030-3	4M 10um 4M 15um 4M 20um	20 x 20 30 x 30 40 x 40	13.3cr 28.1cr 47.1cr	n²/sec (0.30FOV/Sec) n²/sec (0.32FOV/Sec) n²/sec (0.34FOV/Sec)	10um: 100um	2000um / 400um 78.8mils / 15.8mils				
KY8030-3 Inspection Performance	KY8030-3 (HS)	8M 10um 8M 15um 8M 20um	28 x 28 42 x 42 56 x 57	23.8cr 53.5cr 91.2cr	n²/sec (0.33FOV/Sec) n²/sec (0.33FOV/Sec) n²/sec (0.35FOV/Sec)	20um: 200um	1800um / 450um 70.9mils / 17.7mils				
	Illumination		IR-RGB Led Dome Styled Illumination								
	Max Inspection	Size	< FOV								
	Multi-Colored F	PCB Inspection	Possible								
Optional		4-Way Projection Inspection Range (Up to 2mm)									
РСВ	Conveyer Widtl	Max Inspection Size Multi-Colored PCB Inspection Optional Conveyer Width Adjustment Conveyer Fix Type		Automatic							
Handling	Conveyer Fix Type		Front / Rear Fixed (Factory Setting)								
	Supported Inpu	ıt Format	GERBER Data (274X, 274D), ODB++ (Optional)								
	Programing So	ftware	ePM-SPI								
Software	Statistical Process Control Tool		SPC Plus (Histogram, X-bar & R-Chart, X-bar & S-Chart, Cp & Cpk, % Gage R&R / Real Time SPC & Multiple Display / SPC Alarm / Automatic Report from Remote Computer)								
	User-Friendly C	perator	Library Manager & KYCAL (Auto Camera Calibration, Auto Illumination Calibration, Auto Height Calibration)								
	Operating System		WINDOWS 10 IOT ENTERPRISE LTSC 2019								
Add-On Solutions - 1D & 2D Handy Barcode Reader - 1D & 2D Inline Barcode Reader - Auto-Verification - Auto-Rework* - UPS - Standard Calibration Target - Long Board Option		- Offl - ODE - SPC - Offl - Rev - Pan - Fuji - IPC	ine Progra 3++ C Plus for R ine SPC Pl iew Statio asonic AP Nexim Int -CEX Interf	mming Station emote Computer us Station n C Interface (FF/FB) erface ace	- KSMART Solutions (Monitoring and Analy Program Optimizer, Li - KPO Printer (Printer Diagnosis, Prin	s sis, Remote Access, Offline nk Data Analysis, Notification) nter Advisor, Printer Optimizer)					

									The ab	ove spe	cifications	are subject to	change with	out not
						*	Machine dim	nensions, P	CB Size, and clea	irance v	/ill change	if the Auto-Rev	vork option	s select
	М		L		XL									
	Single Lane	Dual Lane	Single Lane	Dual Lane	Single Lane	Dual Lane								
Max PCB Size		Single Mode °	510 x 510mm (20.0 x 20.0in)	Single Mode °	850 x 690mm (33.4 x 27.1in)	Single Mode			0					
	330 x 330mm	330 x 580mm (12.9 x 22.8in)		510 x 580mm (20.0 x 22.8in)		850 x 580mm (33.4 x 22.8in)			Ę					
(X x Y)	(12.9 x 12.9in)	Dual Mode		Dual Mode		Dual Mode								
		330 x 325.5mm (12.9 x 12.8in)		510 x 320mm (20.0 x 12.5in)		850 x 320mm (33.4 x 12.5in)		8						
Min. PCB Size	50 x 50mm (1.9 x 1.9in) 70 x 70mm (2.7				n (2.7x2.7in)		8				<u> </u>	`		
PCB Thickness	0.4 ~ 4mm (0.01 ~ 0.15in) 0.4 ~ 5mm (0.01 ~ 0.19in)		0.6 ~ 8mm (0.02 ~ 0.31in)		Ê					C)			
Max. PCB Weight	Standard : 2kg (4.4lbs), Heavy weight option : 5kg (11.0lbs)			10kg (22.0lbs)		I 950m				ε				
Machine Weight	550kg (1212.5lbs)	600kg (1322.7lbs)	600kg (1322.7lbs)	700kg (1543.2lbs)	850kg (1873.9lbs)	900kg (1984.1lbs)	B Heigh	E		mm	it 950m	(Fr	ont-Fix)	-
Bottom Clearance	50mm (1.9in)					(PC	0~950		1182	B Heigh				
Supplies	220 Vac ± 10%, 50/60Hz , 1 Phase, 5Kgf/cm² (0.45MPa)					2	∞ᇦ			2	-		-	
W	820mm	ı (32.2in)	1000mm (39.3in)		1350mm (53.1in)			_ <u>₩</u>	単				ل ا	1671
D	1265mm (49.8in)	1445mm (56.8in)	1265mm (49.8in)	1445mm (56.8in)	1445mn	n (56.8in)			W		418mm]	D	_
н			1627mn	n (64.0in)										

1627mm (64.0in)

° Please contact us for more information about PCB Sizes. (The above specifications are subject to change without notice.)





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